



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Richard W. Wensel

Serial No.: 10/077,452

Filed: February 14, 2002

For: METHOD AND APPARATUS FOR
TRANSFER MOLDING
ENCAPSULATION OF A
SEMICONDUCTOR DIE WITH
ATTACHED HEAT SINK

Confirmation No.: 4093

Examiner: D. Graybill

Group Art Unit: 2814

Attorney Docket No.: 3061.6US
(96-0893.05/US)

Notice of Allowance Mailed:

February 24, 2003

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

May 15, 2003
Date

Signature

Deidra Pfeil

Name (Type/Print)

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Title begin on page 3 of this paper.

Amendments to the Specification begin on page 4 of this paper.

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Amendments to the Drawings begin on page 5 of this paper and include an attached replacement sheet.

Remarks begin on page 6 of this paper.

IN THE TITLE:

The title has been amended herein. Pursuant to 37 C.F.R. §§ 1.121 and 1.125 (as amended to date), please enter the title as amended.

METHODS ~~AND APPARATUS~~ FOR TRANSFER MOLDING ENCAPSULATION
OF A SEMICONDUCTOR DIE WITH ATTACHED HEAT SINK